

1.- 8. (Previously canceled)

<sup>1</sup> 9. (Currently Amended) The colloid silica slurry wherein it does not have a bad influence, such as corrosion, to a silicon wafer and wiring material on a silicon wafer and inhibits growth of microbes, and whereof preserving stability is high because stability of a particle diameters of colloidal particle is superior and using for a long period continuously is possible, and said colloidal silica slurry is comprised by adding hydrogen peroxide 5 to 100 ppm to lowered metal silica slurry, which metal content is 1 ppm or less and produced from silicate ester, and the pH of colloidal silica slurry is 6.0 to 8.0 and content of colloidal silica is 0.05 ~ 50 weight % ~~hydrogen peroxide from 5 to 100 ppm is added and pH is from 6.0 to 8.0.~~

10. (Canceled)

11. (Canceled)

12. (Canceled)

<sup>2</sup> 13. (Previously Added) The colloidal silica slurry as claimed in claim <sup>1</sup> 9, wherein pH is from 6.5 to 7.5.

<sup>3</sup> 14. (Currently Amended) The colloidal silica slurry as claimed in claim <sup>1</sup> 9, wherein additional quantity of said hydrogen peroxide is from 10 to 50 ppm.

<sup>4</sup> 15. (Previously Added) The colloidal silica slurry as claimed in claim <sup>1</sup> 9, wherein an average particle diameter of said colloidal silica is from 5 to 300 nm.

<sup>5</sup> 16. (Previously Amended) The colloidal silica slurry as claimed in claim <sup>1</sup> 9, wherein an average particle diameter of said colloidal silica is from 10 to 250 nm.